

21. (Previously Amended) A method of forming a conductive path within a laminate, comprising:
providing an opening in the laminate; and
pressing a conductive element into the opening wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.

22. (Original) The method of claim 21, wherein the opening is a hole.

23. (Original) The method of claim 21, wherein the conductive element is a sphere.

24. (Original) The method of claim 21, wherein the conductive element is a cylinder.

27. (Previously Amended) A structure for interconnection between circuit layers, comprising:
a conductive element embedded into a laminate wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate, and wherein the conductive element includes an inner element covered by an outer element.

28. (Original) The structure of claim 27, further including an opening in the laminate that the conductive object is pressed into.

29. (Original) The structure of claim 28, wherein the opening is a hole in the laminate.

30. (Original) The structure of claim 27, wherein the conductive element is a sphere or a cylinder.

31. (Previously Amended) The structure of claim 27, wherein the outer element of the conductive element is a material selected from the group consisting of: glass, copper, brass, and bronze.

32. (Original) The structure of claim 27, wherein the laminate is selected from the group consisting of epoxy, cyanate-epoxy blend, and glass reinforced carrier.

33. (Previously Amended) The method of claim 21, wherein the inner element of the conductive element comprises a material selected from the group consisting of: glass, rubber and plastic.

34. (Previously Amended) The method of claim 21, wherein the outer element of the conductive element comprises a material selected from the group consisting of: copper, brass, gold and bronze.

35. (Previously Amended) The structure of claim 27, wherein the inner element of the conductive element comprises a material selected from the group consisting of: glass, rubber and plastic.

36. A method of forming a conductive path within a laminate, comprising:

providing an opening in the laminate; and

pressing a conductive element into the opening wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate.

37. A structure for interconnection between circuit layers, comprising:

a conductive element embedded into a laminate wherein a portion of the conductive element forms at least one contact pad extending beyond a surface of the laminate.